



(0,50 mm) .0197"

BSH SERIES

BASIC BLADE & BEAM SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BSH

Insulator Material: Black LCP



Contact Material: Phosphor Bronze

Plating: Au or Sn over 50µ" (1,27 µm) Ni

Current Rating: 1.25A per contact @ 80°C ambient

Flammability Rating: UL 94 VO

Operating Temp Range: -55°C to +125°C

Voltage Rating: 125 VAC

Max Cycles: 100

RHS Compliant: Yes

Processing: Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,10 mm) .004" max (030-090) (0,15 mm) .006" max (120-150)

Board Stacking: For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

BSH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
Mates with: BTH		<p>-030, -050, -060, -090, -120, -150</p>			<p>-F = Gold Flash on contact, Matte Tin on tail</p> <p>-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail</p> <p>-C* = Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails</p>	
						<p>-TR = Tape & Reel (120 positions maximum)</p>
AGILENT LOGIC ANALYZER TEST POINT CONNECTOR						Specify: ASP-65067-01

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197

*Processing conditions will affect mated height.

BSH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	RA	WT	OTHER OPTION
Mates with: BTH		<p>-030, -060, -090</p>			<p>-F = Gold Flash on contact, Matte Tin on tail</p> <p>-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail</p>		<p>-GP = Guide Post</p>
						<p>*Note: -C Plating passes 10 year MFG testing</p> <p>Note: Some lengths, styles and options are non-standard, non-returnable.</p>	

Due to technical progress, all designs, specifications and components are subject to change without notice.

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